

SOT1155-1

TFBGA48, plastic thin fine-pitch ball grid array package; 48 balls, 0.5 mm pitch, 4.5 mm x 4.5 mm x 0.8 mm body

20 September 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA48
Package type industry code	TFBGA48
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-11-2009
Manufacturer package code	SOT1155-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	4.4	-	4.5	4.6	mm
A	seated height	0.9	-	1	1.1	mm
A ₂	package height	0.75	-	0.8	0.85	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	A/A



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2. Package outline

TFBGA48: plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 x 4.5 x 0.8 mm SOT1155-1

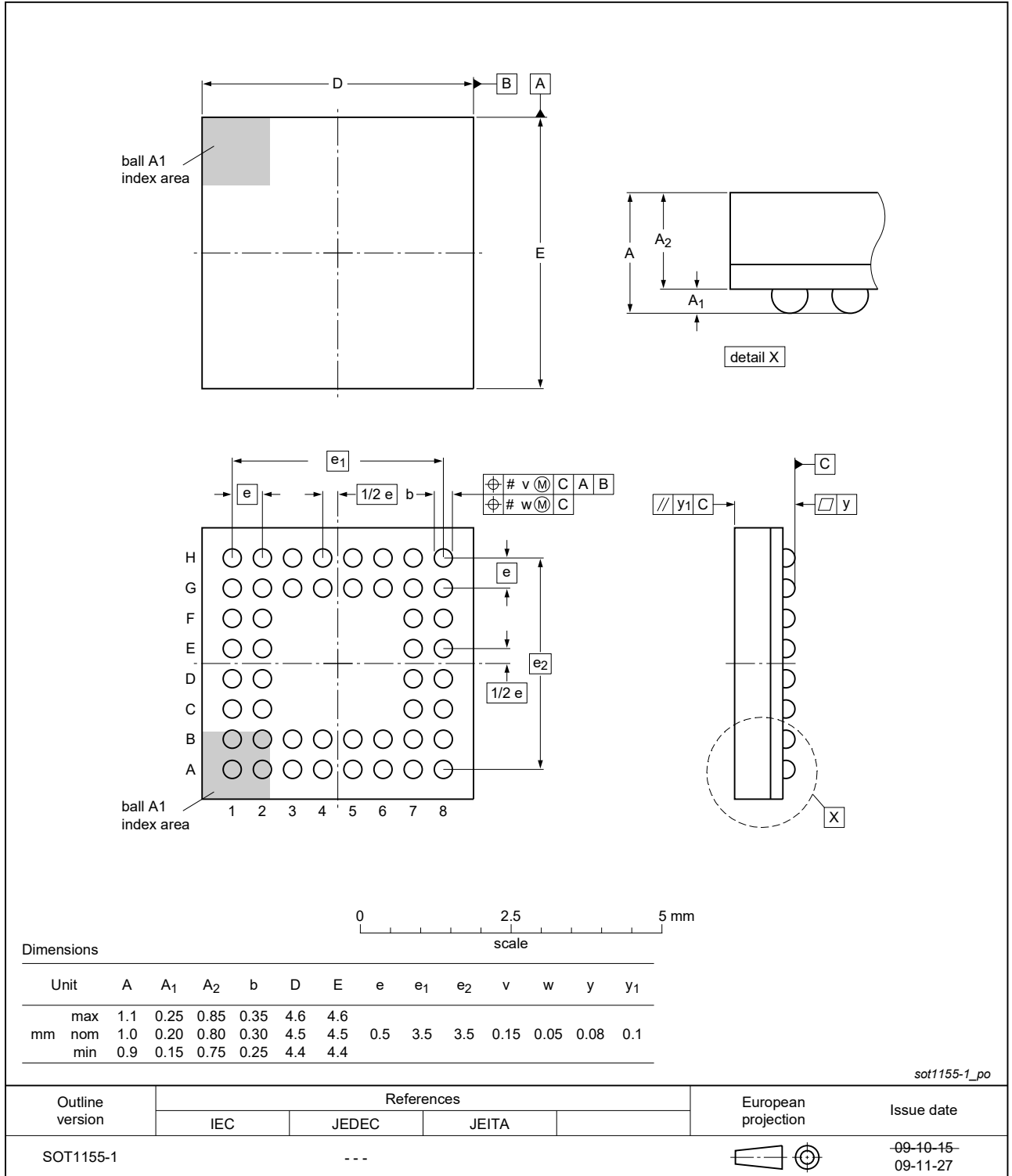
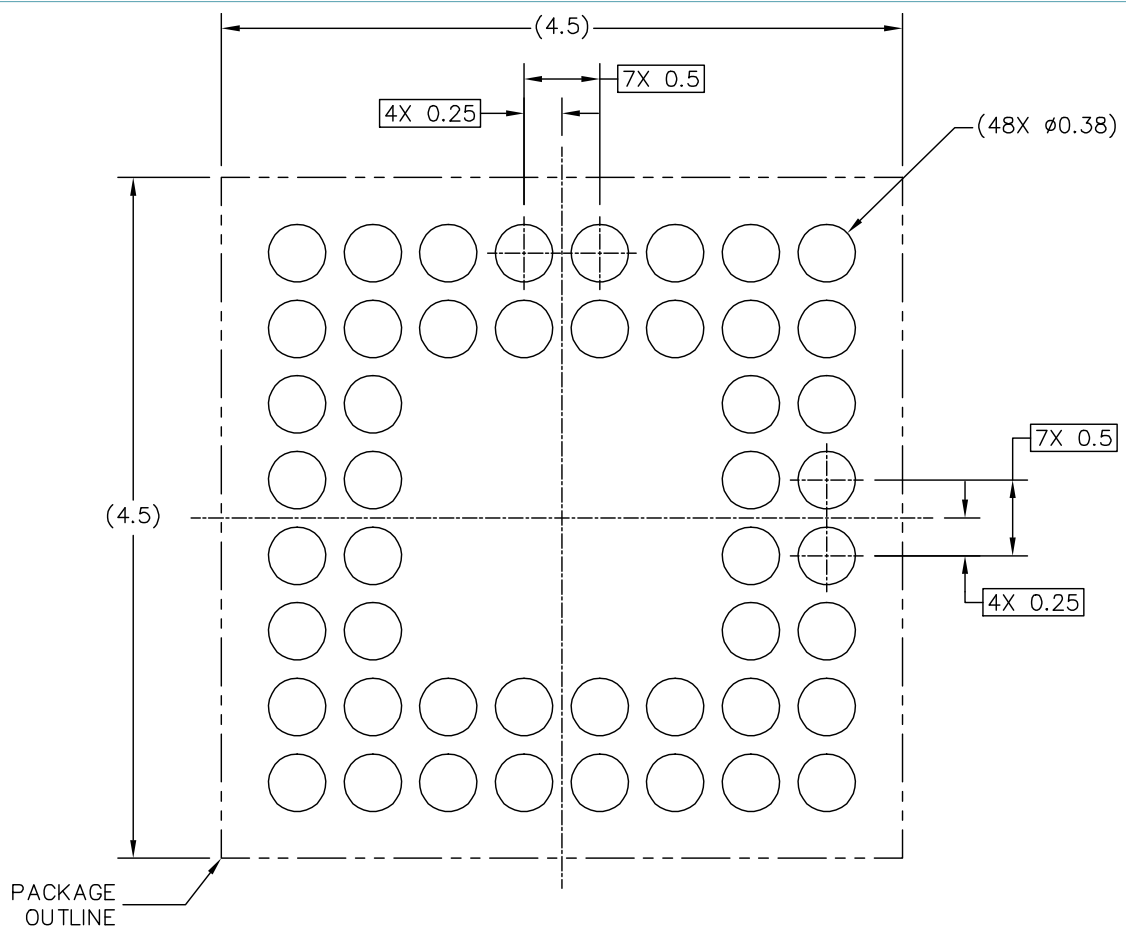


Fig. 1. Package outline TFBGA48 (SOT1155-1)

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3. Soldering

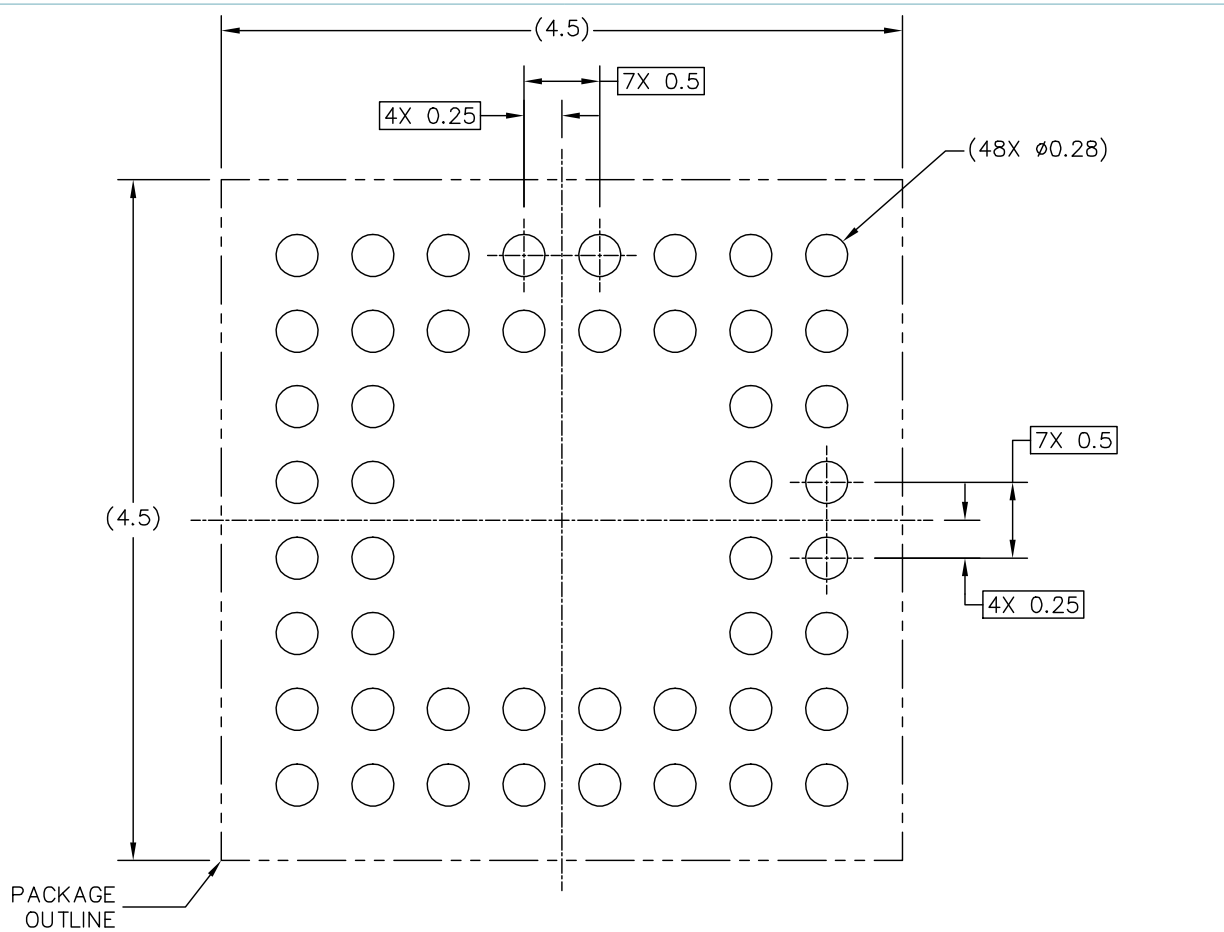


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Fig. 2. Reflow soldering footprint for TFBGA48 (SOT1155-1)

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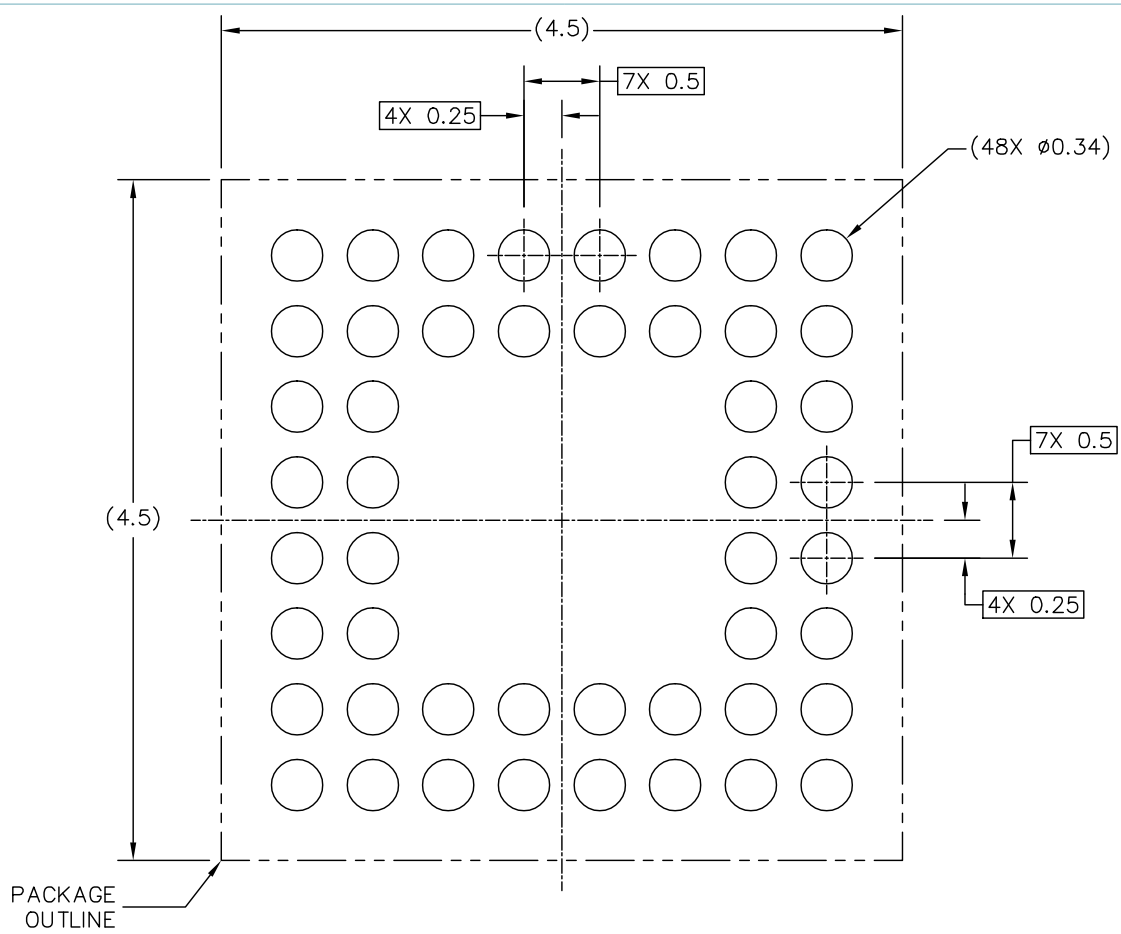


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Fig. 3. Reflow soldering footprint (part 2) for TFBGA48 (SOT1155-1)

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 4. Reflow soldering footprint (part 3) for TFBGA48 (SOT1155-1)

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4. Legal information

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Date of release: 20 September 2017
